# **POWER®** ULTRA MICRO POWER SYSTEM (2.00 mm) .0787" PITCH







**UMPT/UMPS** compared to another small form factor power solution



## **CREEPAGE & CLEARANCE**

UMPT/UMPS					
CREEPAGE	2.20 mm				
CLEARANCE	1.65 mm				

Selectively loading contacts achieves customer specific creepage and clearance requirements.

## **KEY SPECIFICATIONS**

РІТСН	STACK HEIGHTS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	VOLTAGE RATING	LEAD-FREE SOLDERABLE
2.00 mm	5 to 16, 18, 20 mm	Black LCP	Copper Alloy	Sn or Au over 50 μ" (1.27 μm) Ni	-55 °C to +105 °C with Tin -55 °C to +125 °C with Gold	460 VAC/ 650 VDC	Yes

F-221 (Rev 16NOV22)

#### samtec.com/mPOWER

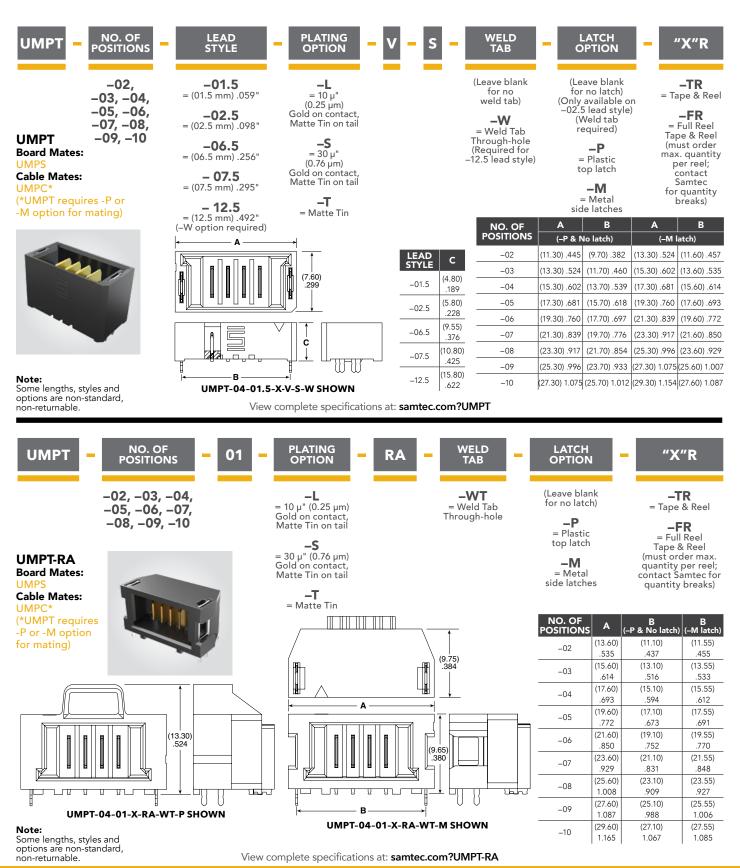
Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

### **FEATURES & BENEFITS**

- Up to 18 A per blade (1 blade powered)
- Design flexibility as a power-only system or a two-piece system for power/signal applications
- Use with Samtec's high-speed connector systems for a unique power/signal system
- Choice of 2 to 10 positions
- 5 mm to 20 mm stack heights available
- Tin or 10 µ" Gold plated power blades; 30 µ" Gold plating available to meet specific regulations
- Optional weld tabs
- Cable-to-board and cable-to-cable systems in development

## **mPOWER**°

## ULTRA MICRO POWER TERMINAL



8

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.